

AN: PAT 2001-34
TI: Electronic component sticking method involves bonding electronic component on adhesive layer of adhesive tape which is cut deeply in shape of cube
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AB: NOVELTY - The adhesive tape (3) is cut deeply and slitted in the shape of small cubes using slitting apparatus (11) on one surface side. The electronic component (12) is bonded on the adhesive layer (4b) of adhesive tape. DETAILED DESCRIPTION - The adhesive tapes are heat shrink base film (4) which contracts on heating. The tape has peeling materials (5a,5b) stuck on both sides. The slitting unit and peeling apparatus (7) are provided adjacently. The peeling material is removed from the slitting surface. A semiconductor chip is bonded on adhesive tape so that dicing line of chip and slitting line of adhesive tape coincides. An INDEPENDENT CLAIM is also included for slitting formation method which involves abutting one surface of tape to slitting unit where supply of adhesive tape is stopped. The slitting line crosses the tape mutually perpendicular so as to notch the tape in the shape of cubes or rectangle.; USE - For electronic components e.g. semiconductor chips. ADVANTAGE - The slitting is done efficiently by cutting deeply and notching a line depending on the need. The necessary number of chips can be temporarily stored with a ring frame. The chips are peeled easily. DESCRIPTION OF DRAWING(S) - The figure shows the schematic side view of adhesive device of electronic component. (Drawing includes non-English language text). Adhesive tape 3 Heat shrink base film 4 Adhesive layer 4b Peeling materials 5a,5b Peeling apparatus 7 Slitting apparatus 11 Electronic component 12
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